



YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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Features

- $BV_{CEO} > 120V$
- Low Saturation Voltage $< 1.5V @ 1A$
- Darlington Transistor $h_{FE} > 2k @ 1A$
- $I_C = 1A$ High Continuous Collector Current
- Specification is Also Available in Eline and SOT223 Package Outlines

Mechanical Data

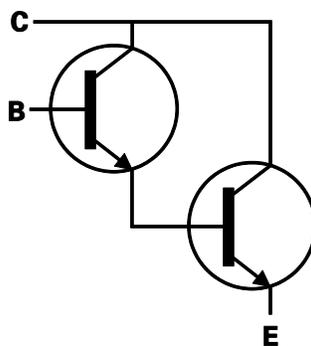
- Case: SOT89
- Case Material: Molded Plastic, "Green" Molding Compound
UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads, Solderable per
MIL-STD-202, Method 208 
- Weight: 0.052 grams (Approximate)

Applications

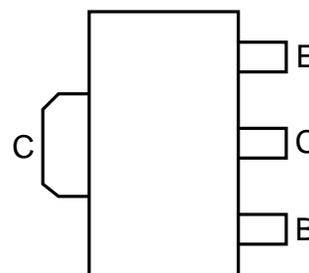
- Various Driving Functions
 - Lamps
 - Motors
 - Relays and Solenoids
- High Output Current Switches



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	140	V
Collector-Emitter Voltage	V_{CEO}	120	V
Emitter-Base Voltage	V_{EBO}	10	V
Continuous Collector Current	I_C	1	A
Peak Pulse Current	I_{CM}	4	A

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation	(Note 5)	P_D	0.9	W
	(Note 6)		1	
Thermal Resistance, Junction to Ambient	(Note 5)	$R_{\theta JA}$	139	$^\circ\text{C/W}$
	(Note 6)		125	
Thermal Resistance, Junction to Leads	(Note 7)	$R_{\theta JL}$	5.2	$^\circ\text{C/W}$
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	2,000	V	2
Electrostatic Discharge - Machine Model	ESD MM	200	V	B

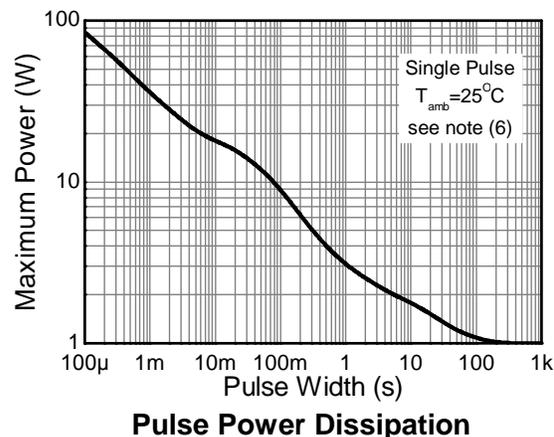
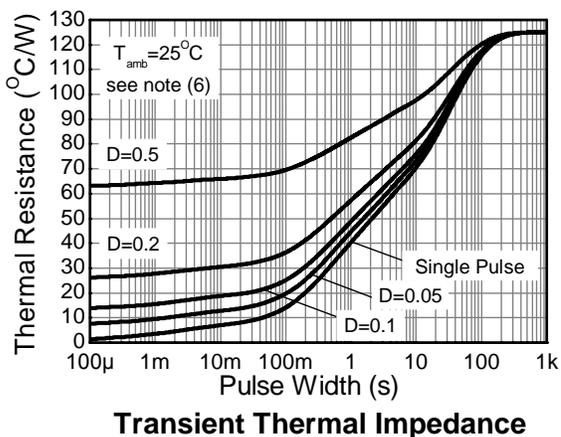
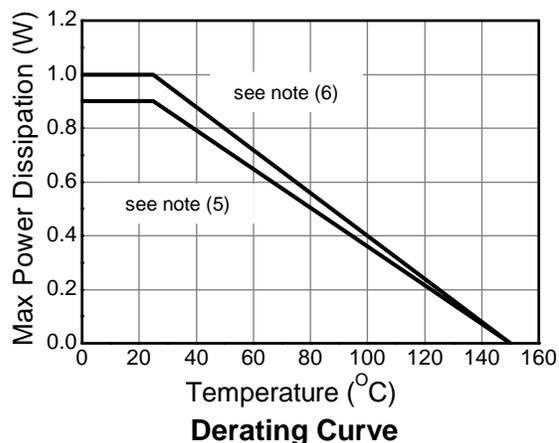
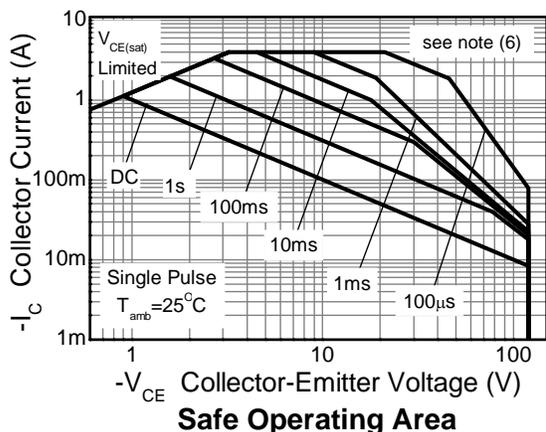
Notes: 5. For a device mounted with the exposed collector pad on 15mm x 15mm 1oz copper that is on a single-sided 1.6mm FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

6. Same as Note 5, except the device is mounted on 25mm x 25mm 1oz copper.

7. Thermal resistance from junction to solder-point (at the end of the leads).

8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

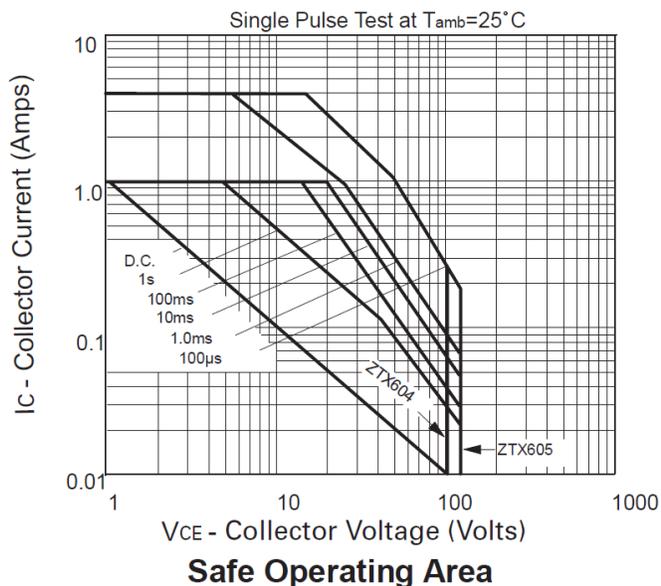
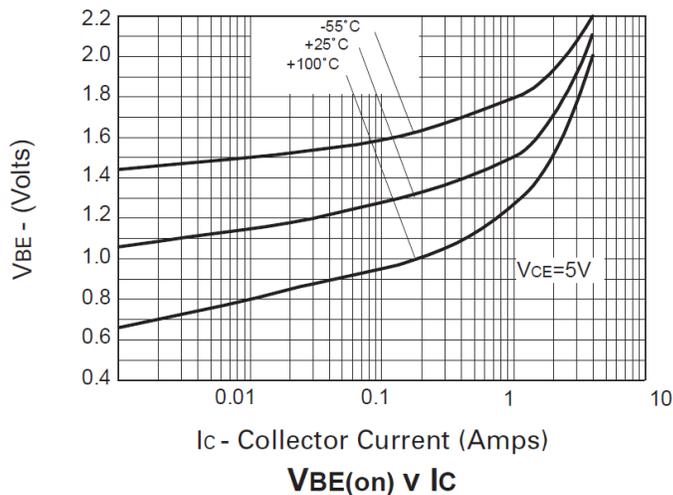
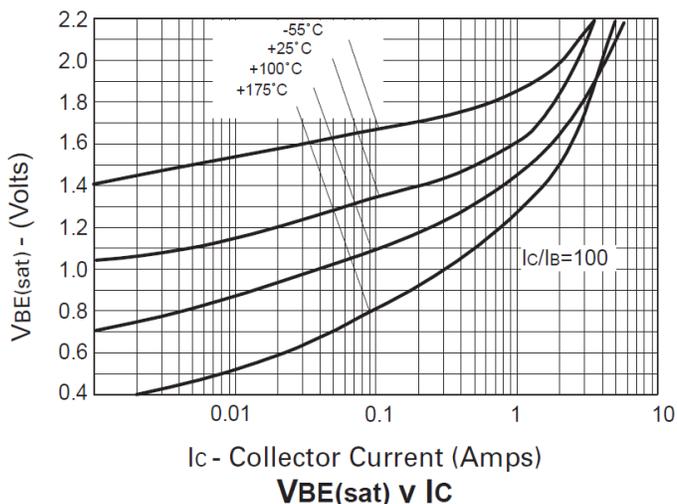
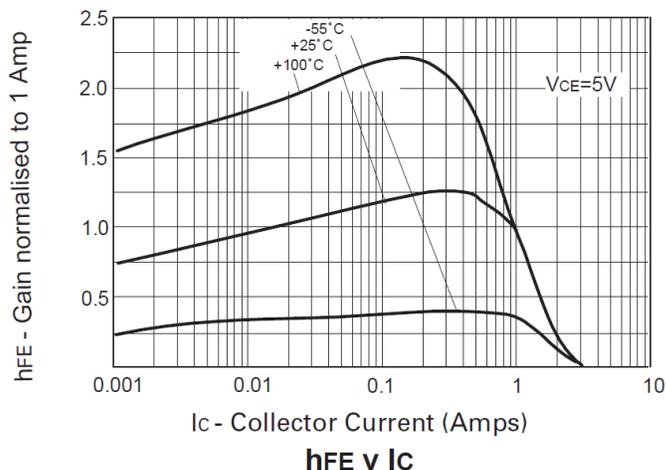
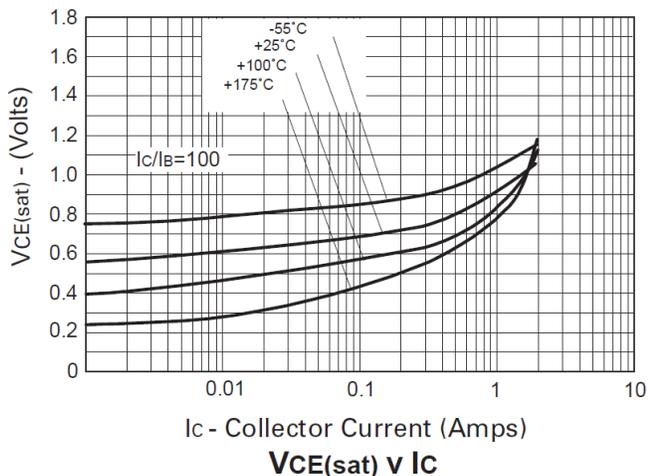


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

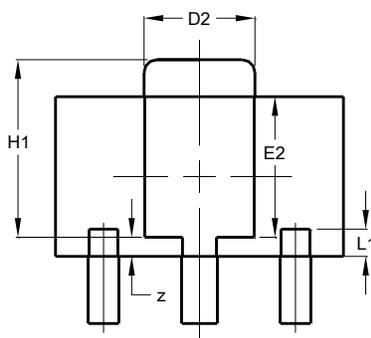
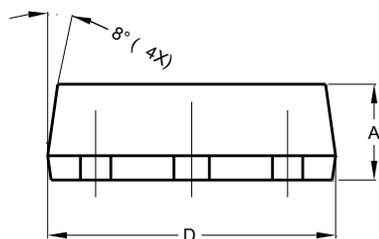
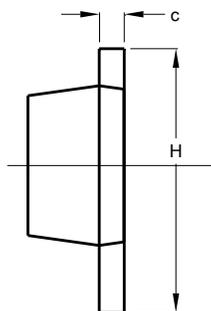
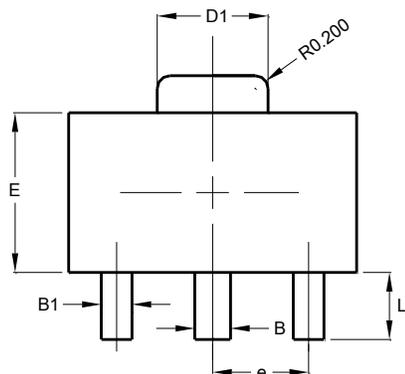
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	140	—	—	V	$I_C = 100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 9)	BV_{CEO}	120	—	—	V	$I_{CEO} = 10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	10	—	—	V	$I_{EBO} = 100\mu\text{A}$
Collector Cut-off Current	I_{CBO}	—	—	100 10	nA μA	$V_{CB} = 10\text{V}$ $V_{CB} = 120\text{V}, T_A = +100^\circ\text{C}$
Emitter-base Cut-off Current	I_{EBO}	—	—	0.1	μA	$V_{EB} = 8\text{V}$
Collector Emitter Cut-Off Current	I_{CES}	—	—	10	μA	$V_{CES} = 120\text{V}$
ON CHARACTERISTICS (Note 9)						
Static Forward Current Transfer Ratio	h_{FE}	2k 5k 2k 0.5	— — — —	— — 100k —	—	$I_C = 50\text{mA}, V_{CE} = 5\text{V}$ $I_C = 500\text{mA}, V_{CE} = 5\text{V}$ $I_C = 1\text{A}, V_{CE} = 5\text{V}$ $I_C = 2\text{A}, V_{CE} = 5\text{V}$
Collector-Emitter Saturation Voltage	$V_{CE(SAT)}$	—	—	1 1.5	V	$I_C = 250\text{mA}, I_B = 0.25\text{mA}$ $I_C = 1\text{A}, I_B = 1\text{mA}$
Base-Emitter Saturation Voltage	$V_{BE(SAT)}$	—	—	1.8	V	$I_C = 1\text{A}, I_B = 1\text{mA}$
Base-Emitter Turn-On Voltage	$V_{BE(ON)}$	—	—	1.7	V	$I_C = 1\text{A}, V_{CE} = 5\text{V}$
SMALL SIGNAL CHARACTERISTICS (Note 9)						
Transition Frequency	f_T	150	—	—	MHz	$I_C = 100\text{mA}, V_{CE} = 10\text{V}$ $f = 20\text{MHz}$
Input Capacitance	C_{ibo}	—	90	—	pF	$V_{CB} = 500\text{mV}, f = 1\text{MHz}$
Output Capacitance	C_{obo}	—	15	—	pF	$V_{CB} = 10\text{V}, f = 1\text{MHz}$
Turn-On Time	t_{ON}	—	0.5	—	μs	$I_C = 500\text{mA}, V_{CE} = 10\text{V}$ $I_{B1} = -I_{B2} = 0.5\text{mA}$
Turn-Off Time	t_{OFF}	—	1.6	—	μs	$I_C = 500\text{mA}, V_{CE} = 10\text{V}$ $I_{B1} = -I_{B2} = 0.5\text{mA}$

 Note: 9. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

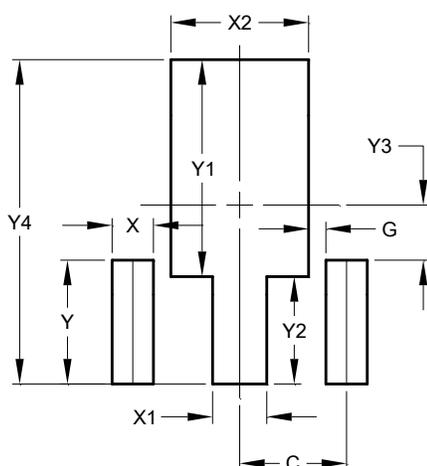


Package Outline Dimensions



SOT89			
Dim	Min	Max	Typ
A	1.40	1.60	1.50
B	0.50	0.62	0.56
B1	0.42	0.54	0.48
c	0.35	0.43	0.38
D	4.40	4.60	4.50
D1	1.62	1.83	1.733
D2	1.61	1.81	1.71
E	2.40	2.60	2.50
E2	2.05	2.35	2.20
e	-	-	1.50
H	3.95	4.25	4.10
H1	2.63	2.93	2.78
L	0.90	1.20	1.05
L1	0.327	0.527	0.427
z	0.20	0.40	0.30
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	1.500
G	0.244
X	0.580
X1	0.760
X2	1.933
Y	1.730
Y1	3.030
Y2	1.500
Y3	0.770
Y4	4.530

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.